IN THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently amended) A method for manufacturing an organic electroluminescent display device, ~~wherein~~ comprising: applying an arrangement of layers ~~is applied~~ to a substrate such[[,]] that ~~in a first direction,~~ first conductors extend in a first direction and ~~as well as~~ second conductors extend in a second direction, providing ~~while~~ between crossings of the first and second conductors an organic electroluminescent compound ~~has been provided~~ which, under the influence of a voltage, emits light, the substrate being manufactured from plastic and having a surface structure which forms a boundary for at least a number of the layers which are applied, applying a first conductive layer ~~being applied~~ by ~~means of~~ a layer application process, the surface structure of the plastic substrate being provided with a shadowing structure which is such that with the layer application process, parts of [[this]] the shadowing structure are ~~hardly~~ substantially not covered~~, if at all,~~ with the ~~respective~~ first conductive layer, the shadowing structure being such that the electrical resistance prevailing there is ~~great relative to~~ larger than the resistance in the rest of the first conductive layer.

2. (Currently amended) A method according to claim 1, wherein the manufacture of the substrate comprises ~~takes place with the aid of~~ an infection molding process.

3. (Original) A method according to claim 2, wherein in the injection molding process use is made of an injection molding mold which is provided with a negative image of the desired surface structure of the substrate.

4. (Currently amended) A method according to claim 1, wherein the manufacture of the substrate comprises ~~takes place with the aid of~~ embossing, photopolymeric replication or a ~~similar~~ plastic formation process.

5. (Currently amended) A method according to ~~any one of the preceding claims~~ claim 1, wherein after the manufacture of the plastic substrate, a first transparent encapsulation layer is applied to the substrate.

6. (Original) A method according to claim 5, wherein the first transparent encapsulation layer is a nitride-oxide-nitride layer (NON-layer).

7. (Currently amended) A method according to claim 5 [[or 6]], wherein [[this]] the first transparent encapsulation layer is applied ~~with the aid of~~ by a deposition technique~~, such as, for instance, a PVD-, CVD- or PECVD-process~~.

8. (Currently amended) A method according to ~~any one of claims 5-7~~ claim 5, wherein after the application of the first transparent encapsulation layer, [[a]] the first conductive layer is applied such that a number of parallel first conductors extending in [[a]] the first direction [[is]] are provided which are mutually insulated from each other by an insulator, ~~while~~ wherein parts of the first conductors extend in pixel pits or sub-pixel pits of the surface structure of the substrate

9. (Original) A method according to claim 8, wherein the layer application process for the first conductive layer is a sputtering process.

10. (Currently amended) A method according to claim 9, wherein the shadowing structure comprises a number of parallel, narrow and deep grooves, the width and the depth of the grooves being such that at least a part of the side walls and/or the bottom of these grooves are ~~hardly~~ substantially not covered~~, if at all,~~ with the first conductive layer in the sputtering process.

11. (Currently amended) A method according to claim 8, wherein the first conductive layer is applied ~~with the aid of~~ by a printing operation~~, such as for instance inkjet printing, silkscreen printing, electrostatic printing or thermal transfer printing~~.

12. (Currently amended) A method according to ~~any one of claims 8-11~~ claim 8, wherein after the application of the first conductive layer, at least in the pixel pits or sub-pixel pits, a hole injecting layer ~~such as for instance a PDDT-layer~~ is applied.

13. (Currently amended) A method according to claim 11, wherein the first conducive layer [[also]] forms a hole injecting layer in the pixel pits or sub-pixel pits~~, such as for instance a PDOT layer~~.

14. (Currently amended) A method according to ~~any one of claims 12 or 13~~ claim 12, wherein after application of the hole injecting layer a light emitting [[light]] layer is provided locally in at least the pixel pits or sub-pixel pits~~, such as for instance a PPV layer~~.

15. (Currently amended) A method according to ~~at least~~ claim 8, wherein at least those parts of the first conductive layer which are not covered with ~~a light emitting layer~~ the organic electroluminescent compound and which, in a following process [[step]], will be covered by a second conductive layer, are provided with an insulating covering prior to said following process [[step]].

16. (Currently amended) A method according to claim 15, wherein the insulating covering is applied with a printing operation~~, such as, for instance, by means of inkjet printing~~.

17. (Currently amended) A method according to claim 16, wherein the insulating [[layer]] covering is formed from a UV-curing varnish.

18. (Currently amended) A method according to ~~claims 10 and 16 or claims 10 and 17~~ claim 16, wherein the deep grooves forming the shadowing structure are filled up with the insulating covering.

19. (Currently amended) A method according to ~~any one of the preceding claims~~ claim 1, wherein the shape of the surface structure, after application of at least one layer, is adapted by a transforming technique~~, such as, for instance, a local thermal treatment~~.

20. (Currently amended) A method according to claim 19, wherein the transforming technique is a local thermal treatment [[is]] carried out ~~with the aid of a~~ by laser operation or ~~with the aid of~~ by [[a]] local infrared irradiation.

21. (Currently amended) A method according to ~~any one of the preceding claims~~ claim 1, wherein ~~an additional~~ a relief structure is provided on the substrate already provided with a number of layers~~, for forming a relief structure desired~~ for the application of a following layer.

22. (Currently amended) A method according to claim 21, wherein the ~~additional~~ relief structure is provided ~~with the aid of~~ by a printing operation, while using a curing varnish~~, preferably a UV-curing varnish~~.

23. (Currently amended) A method according to ~~claims 8 and 21 or claims 8 and 22~~ claim 8, wherein after application of the insulator, a relief structure is provided for forming channels extending parallel to each other, [[while]] wherein the channel direction is perpendicular to said first direction in which the first conductors extend.

24. (Currently amended) A method according to claim 15, wherein after application of the insulating covering, a second conductive layer is provided such that in ~~simple manner,~~ a number of parallel second conductors are provided extending in a second direction and which are mutually insulated from each other, while parts of the second conductors extend in pixel pits or sub-pixel pits of the surface structure of the substrate.

25. (Original) A method according to claim 24, wherein the second direction is perpendicular to the first direction.

26. (Currently amended) A method according to claim 24 [[or 25]], wherein the second conductive layer is applied with a printing process~~, such as, for instance, inkjet printing, silkscreen printing, electrostatic printing or thermal transfer printing~~.

27. (Currently amended) A method according to claim ~~23 and any one of claims~~ 24[[-26]], wherein the second conductive layer is applied in [[said]] channels extending parallel to each other.

28. (Currently amended) A method according to ~~any one of claims 24-27~~ claim 24, wherein, prior to the application of the second conductive layer and after the application of

the insulating covering, an electron injecting layer ~~such as a calcium, magnesium, lithium fluoride or barium layer~~ is applied to the substrate.

29. (Currently amended) A method according to claim [[28]] 54, wherein the barium layer is applied with a PVD-process.

30. (Currently amended) A method according to ~~any one of claims 24-27~~ claim 24, wherein after the application of the second conductive layer at least one encapsulation layer is applied.

31. (Currently amended) A substrate ~~suitable and intended~~ for use in ~~a method according to any one of the preceding claims for~~ manufacturing an organic electroluminescent display device, the ~~method~~ substrate comprising ~~the step of applying~~ a first conductive layer applied by ~~means of~~ a layer application process, wherein the substrate ~~has been manufactured from~~ comprises plastic and has a surface structure forming a boundary for ~~at least a number of the layers to be applied~~ the first conductive layer, the surface structure ~~of plastic substrate being provided with~~ comprising a shadowing structure which is such that with the layer application process, parts of [[this]] the shadowing structure are substantially not ~~hardly~~ covered~~, if at all,~~ with the ~~respective~~ first conductive layer, the shadowing structure being such that the electrical resistance prevailing there is ~~great relative to~~ larger than the resistance in the rest of the first conductive layer.

32. (Original) A substrate according to claim 31, wherein the surface structure comprises a number of pixel pits or sub-pixel pits.

33. (Currently amended) A substrate according to claim 31 [[or 32]], wherein the layer application process is ~~surface structure comprises a shadowing structure which is such that with~~ a sputtering process, and parts of [[this]] the shadowing structure are not covered with the ~~respective~~ first conductive layer.

34. (Original) A substrate according to claim 33, wherein the shadowing structure comprises a number of parallel, narrow and deep grooves, wherein the width and the depth of

the grooves is such that at least a part of the side wells and/or the bottom of these grooves are not covered with the first conductive layer in the sputtering process.

35. (Currently amended) A substrate according to ~~any one of claims 31-34~~ claim 31, wherein the surface structure is releasing such that it can be taken from a mold which is provided with a negative image of the surface structure.

36. (Currently amended) A substrate according to ~~any one of claims 31-35~~ claim 31, wherein the substrate is an injection molding product.

37. (Currently amended) A substrate according to ~~any one of claims 31-36~~ claim 32, wherein, in the pixel pits or sub-pixel pits, a structure ~~has been~~ is provided which influences [[the]] generated light passing the structure.

38. (Currently amended) A substrate according to ~~any one of claims 31-36~~ claim 32, wherein at [[the]] a side of the substrate remote from the pixel pits or sub-pixel pits, a structure ~~has been~~ is provided which influences [[the]] generated light passing the structure.

39. (Currently amended) A substrate according to claim 37[[or 38]], wherein the structure comprises a Fresnel lens.

40. (Currently amended) A substrate according to ~~any one of claims~~ claim 37[[-39]], wherein the structure has a converging effect on the light issuing through the structure.

41. (Currently amended) A substrate according to ~~any one of claims~~ claim 37[[-39]], wherein the structure has a diverging effect on the light issuing through the structure.

42. (Currently amended) A substrate according to ~~any one of claims 31-41~~ claim 32, wherein in the pixel pits or sub-pixel pits a structure ~~has been~~ is provided, ~~designed for improving the distribution of~~ configured to distribute liquid for forming the layers provided in the pixel pits or substantially-pixel pits.

43. (Currently amended) A substrate according to ~~any one of claims 31-42~~ claim 32, wherein in the pixel pits or sub-pixel pits a contact surface enlarging structure ~~has been~~ is provided.

44. (Currently amended) A substrate according to ~~any one of claims~~ claim 42[[or 43]], wherein the structure comprises capillary grooves.

45. (Currently amended) An organic electroluminescent display device ~~manufactured while using a method according to any acre of claims 1-30 starting from~~ comprising a substrate according to ~~any one of claims~~ claim 31[[-44]].

46. (New) A method according to claim 7, wherein the deposition technique comprises a PVD, CVD or PECVD process.

47. (New) A method according to claim 11, wherein the printing operation comprises inkjet printing, silkscreen printing, electrostatic printing, or thermal transfer printing.

48. (New) A method according to claim 12, wherein the hole injecting layer comprises a PDOT-layer.

49. (New) A method according to claim 13, wherein the hole injecting layer comprises PDOT-layer.

50. (New) A method according to claim 12, wherein the light emitting layer is a PPV layer.

51. (New) A method according to claim 16, wherein the printing operation comprises inkjet printing.

52. (New) A method according to claim 22, wherein the curing varnish comprises a UV curing varnish.

53. (New) A method according to claim 26, wherein the printing process comprises inkjet printing, silkscreen printing, electrostatic printing, or thermal transfer printing.

54. (New) A method according to claim 28, wherein the electron injecting layer comprises a calcium, magnesium lithium fluoride, or barium layer.